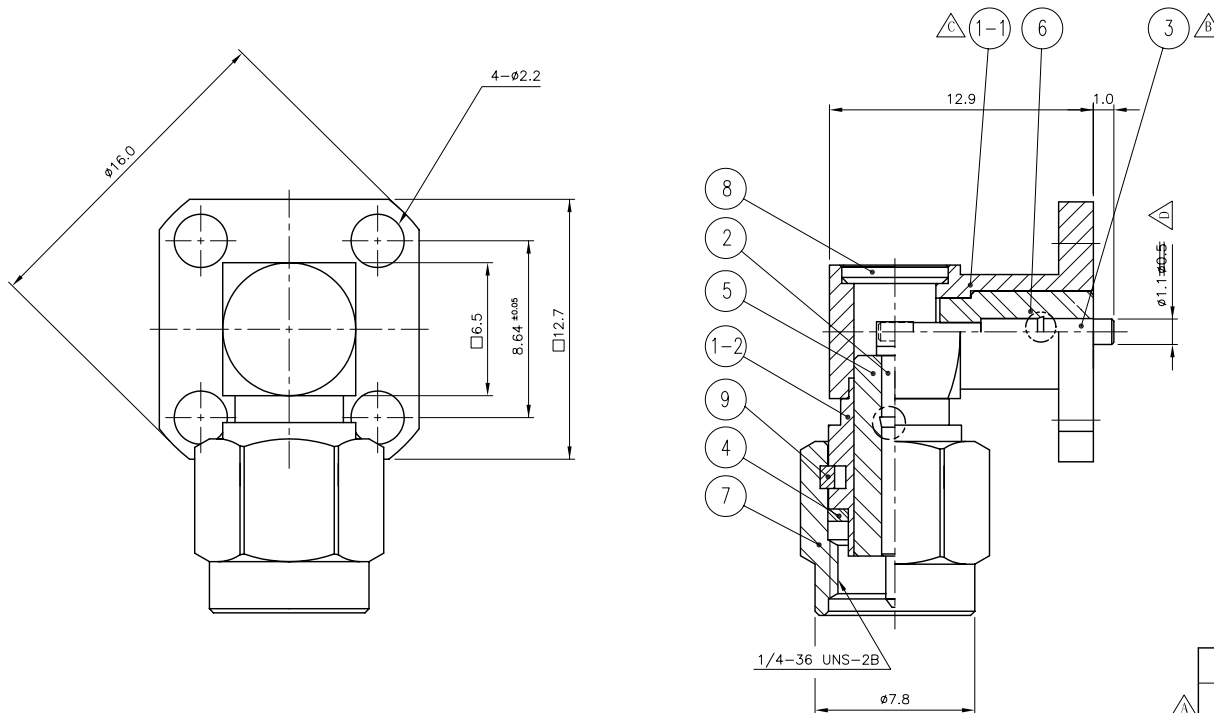


REVISION		
REV	DESCRIPTION	DATE
IR	최초 개정	2008.08.25.
A	(설번)연구2005-142 BODY에 COVER 삽입관련 공차변경(1.3009~>1.2036)	2005.05.24.
B	생산성 향상(설번No. 2005-168) (플공정시 PIN 절단현상 개선으로 인한 뉘시비늘 추가)	2005.07.20.
C	신뢰성 향상 (설번No.연구2006-149) (PIN 절단 방지 뉘시비늘 삽입)	2006.07.27.
D	설번차리No.200904-0005 PCB용 관 간격에 커서 납땜시 SHORT 발생 개선	2009.04.20.



9	SPRING RING	1	SUS	부동태 처리	DSR00002-5/1 (R2001)
8	COVER	1	BsS	Gold Plate	DCO00038-5/1 (L2036)
7	COUPLING CAP	1	MBsBD	Gold Plate	DCU00005-5/1 (K2001)
6	INSULATOR	1	TEFLON		DIN00241-N/1 (H2262)
5	INSULATOR	1	TEFLON		DIN00111-N/1 (H2035)
4	GASKET	1	SILICONE RUB		DGK00004-N/1 (G2001)
3	CONTACT	1	MBsBD	Gold Plate	DCT00111-5/1 (E2383)
2	CONTACT	1	MBsBD	Gold Plate	DCT00305-5/1 (E2037)
1-2	BODY (B)	1	MBsBD	Gold Plate	DBD00258-3/1
1-1	BODY (A)	1	MBsBD	Gold Plate	DBD00151-5/1 DBD00230-3/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE	2009. 04. 20.
	Angle	APPROVED BY	S.J.YOUN
MATERIAL	±1°	CHECKED BY	E.H.KIM
		DRAWN BY	I.C.KIM
FINISH		SCALE	4/1
		UNIT	mm

		RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
KJ COMTECH CO.,LTD.		TITLE
SMA-LP-H4-R		
A3	DWG NO.	CN01401-7/2
REVISION	D	SHEET 1 of 1